**Att. No. 1**

**ORDER DESCRIPTION**

1. **Object of the contract**

The subject of the order is the supply of semiconductors wafers listed below by name and quantity needed:

1. InP N 2” SSP 30 pieces

2. InP N 3” SSP 30 pieces

3. InP N 4” SSP 50 pieces

1. **Parameters**

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| Product name | Parametrer | Specification |
| **2” InP N-type** **Doped with S**  | Diameter 2” Thickness: 350±25 µmDiameter: 50.0±0.5 mm | Grade: | Prime, Epi-ready |
| Orientation: | (100)±0.3o |
| Primary Flat: | EJ (0-1-1) ±1o |
| Secondary Flat | EJ (0-11) ±1o |
| Carrier Conc.: | Min 1E18/cm3 |
| EPD (Average): | ≤5000/cm2 max |
| Surface Finish: | SSP (single side polished) Side 1: Polished Side 2: Etched |
| Packaging: | ePAK, individual box, sealed with N2 in a moisture-stopping metallic foil bag, done in class 100 clean room. |
| Product name | Parametrer | Specification |
| **3” InP N-type** **Doped with S**  | Diameter 3”Thickness: 600±30 µmDiameter: 76.2±0.3 mm | Grade: | Prime, Epi-ready |
| Orientation: | (100)±0.3o |
| Primary Flat: | EJ (0-1-1) ±1o |
| Secondary Flat | EJ (0-11) ±1o |
| Carrier Conc.: | Min 1E18/cm3 |
| EPD (Average): | ≤5000/cm2 max |
| Surface Finish: | SSP (single side polished) Side 1: Polished Side 2: Etched |
| Packaging: | ePAK, individual box, sealed with N2 in a moisture-stopping metallic foil bag, done in class 100 clean room. |

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| Product name | Parameter  | Specification |

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| **4” InP N-type** **Doped with S**  | Diameter 4”Thickness: 625±25 µmDiameter: 100.0±0.3 mm | Grade: | Prime, Epi-ready |
| Orientation: | (100)±0.3o |
| Primary Flat: | EJ (0-1-1) ±1o |
| Secondary Flat | EJ (0-11) ±1o |
| Carrier Conc.: | Min 1E18/cm3 |
| EPD (Average): | ≤5000/cm2 max |
| Surface Finish: | SSP (single side polished) Side 1: Polished Side 2: Etched |
| Packaging: | ePAK, individual box, sealed with N2 in a moisture-stopping metallic foil bag, done in class 100 clean room. |